# IC Package Substrate Report 2019

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# Outline of the Survey

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**1. Objective of this report**

The purpose of this report is to provide relevant people in this market basic information to help them establish their business strategies by analyzing the trends of the IC Package Substrates for BGA and CSP.

**2. Period of Survey**

June 2019 - November 2019

**3. Survey method**

Direct interviews, questionnaires, newspapers, academic, technical journals and internet survey.

**4. Remarks**

- The market size is shown in global basis unless noted so.
- The data is calendar year basis.
- The classification between CSP and BGA in this report is ball pitch below 0.8mm is CSP and over 0.8mm is BGA.

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**<Japanese Manufacturers>**

1. Ibiden Co., Ltd.
2. SHINKO ELECTRIC INDUSTRIES CO., LTD.
3. KYOCERA Corporation
4. Toppan Printing Co., LTD

**＜Taiwanese Korean and Other Manufacturers＞**

1. Unimicron Technology Corporation
2. Nan Ya Printed Circuit Board Corporation
3. Kinsus Interconnect Technology Corporation
4. Samsung Electro-Mechanics Company Limited
5. AT&S Austria Technologie & Systemtechnik AG

**＜Survey items＞**

1. Company Profile
2. IC Package Substrate Business
   - 2-1. Manufacturing Sites
   - 2-2. Major Products
   - 2-3. Actual Sales of IC Package Substrates

# Report Samples

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## Market Size Forecast of IC Package Substrates (2015-2028)

| | | | 2015 | 2018 | 2019 | 2020 | 2022 | 2025 | 2028 |
|---|---|---|---|---|---|---|---|---|---|
| Volume: Million Units | BGA | FCBGA | | | | | | | |
| | | WBBGA | | | | | | | |
| | | Sub total | | | | | | | |
| | CSP | FCCSP | | | | | | | |
| | | WBCSP | | | | | | | |
| | | Sub total | | | | | | | |
| | Total | | | | | | | | |
| Value: Million USD | BGA | FCBGA | | | | | | | |
| | | WBBGA | | | | | | | |
| | | Sub total | | | | | | | |
| | CSP | FCCSP | | | | | | | |
| | | WBCSP | | | | | | | |
| | | Sub total | | | | | | | |
| | Total | | | | | | | | |

(Estimated by JMS)

## Market Size Forecast of FCCSP Substrates (2015-2028)

| | | | 2015 | 2018 | 2019 | 2020 | 2022 | 2025 | 2028 |
|---|---|---|---|---|---|---|---|---|---|
| Volume: Million Units | Build-up Substrates | SAP | | | | | | | |
| | | MSAP | | | | | | | |
| | | Subtractive | | | | | | | |
| | ETS | | | | | | | | |
| | Total | | | | | | | | |
| Value: Million USD | Build-up Substrates | SAP | | | | | | | |
| | | MSAP | | | | | | | |
| | | Subtractive | | | | | | | |
| | ETS | | | | | | | | |
| | Total | | | | | | | | |

(Estimated by JMS)

## Market Size of FCBGA Substrates by Applications in 2018

| CY2018 | | MPU | GPU | Chipset | FPGA/Others | Total |
|---|---|---|---|---|---|---|
| Volume: Million Units | Ibiden | | | | | |
| | Unimicron | | | | | |
| | Shinko | | | | | |
| | Nan Ya | | | | | |
| | Kinsus | | | | | |
| | Kyocera | | | | | |
| | SEMCO | | | | | |
| | AT&S | | | | | |
| | Toppan | | | | | |
| | Others | | | | | |
| | Total | | | | | |
| Value: Million USD | Ibiden | | | | | |
| | Unimicron | | | | | |
| | Shinko | | | | | |
| | Nan Ya | | | | | |
| | Kinsus | | | | | |
| | Kyocera | | | | | |
| | SEMCO | | | | | |
| | AT&S | | | | | |
| | Toppan | | | | | |
| | Others | | | | | |
| | Total | | | | | |

(Estimated by JMS)

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## Market Size of FCBGA Substrates by Layer Counts in 2018

| CY2018 | | 1-N-1 | 2-N-2 | 3-N-3 | 4-N-4 | 5-N-5 | Others | Total |
|---|---|---|---|---|---|---|---|---|
| Volume: Million Units | Ibiden | | | | | | | |
| | Unimicron | | | | | | | |
| | Shinko | | | | | | | |
| | Nan Ya | | | | | | | |
| | Kinsus | | | | | | | |
| | Kyocera | | | | | | | |
| | SEMCO | | | | | | | |
| | AT&S | | | | | | | |
| | Toppan | | | | | | | |
| | Others | | | | | | | |
| | Total | | | | | | | |
| Value: Million USD | Ibiden | | | | | | | |
| | Unimicron | | | | | | | |
| | Shinko | | | | | | | |
| | Nan Ya | | | | | | | |
| | Kinsus | | | | | | | |
| | Kyocera | | | | | | | |
| | SEMCO | | | | | | | |
| | AT&S | | | | | | | |
| | Toppan | | | | | | | |
| | Others | | | | | | | |
| | Total | | | | | | | |

(Estimated by JMS)

※Others=6-N-6 or more, 2.5D Packaging

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# Report Samples

## AT & S Austria Technologie & Systemtechnik AG

https://ats.net/

### 1. Company Profile

| Headquarters | Fabriksgasse 13, 8700 Leoben Osterreich, Austria | | | | |
|---|---|---|---|---|---|
| Capital | 141 | Number of Employees | 10,000 (including leased personnel) | | |
| | 2014 | 2015 | 2016 | 2017 | 2018 |
| Consolidated Sales | | | | | |

Unit: Million Euro  Fiscal year-end: December  Capital and Number of Employees: as of March 31, 2019

2-2. Manufacturing Sites of IC Package Substrates

| | Major Products | Technologies | Capacity (㎡/Y) |
|---|---|---|---|
| Shanghai Plant | HDI | | |
| Chongqing Plant | IC PKG, SLP | | |

(Estimated by JMS)

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*Branch code: 105
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*Account Number: 105-1653912
*Account Name: Japan Marketing Survey Co., Ltd.

Please make the payment in 15 business days. Please transfer the payment the way the amount above will be deposited in our account.